EVERSPIN®
TECHNOLOGIES

Product and Process Change Notice

PCN No.	PCN02956	**PCN Date**	10/3/2016	**Effective Date**	11/7/2016
Title	**Additional Assembly Site for 16Mb (x16) 54p TSOP Package**				

Type: Major Change

Everspin is adding ChipMOS as a qualified assembly site for the 16Mb(x16) 54p TSOP package.

Reason For Change

In order to increase capacity and improve supply flexibility, Everspin is adding ChipMOS as an assembly site for the 54p TSOP package.

Affected Products

Part Number	Description	Part Number	Description
MR4A16BYS35	Commercial Temp.	**MR4A16BYS35R**	Commercial Temp., T&R
MR4A16BCYS35	Industrial Temp.	**MR4A16BCYS35R**	Industrial Temp., T&R

Purpose: Detail Description of Change

ChipMOS is a well-established assembly subcontractor. Everspin is qualifying ChipMOS to supply the 54p TSOP2 package type on our 16Mb (x16) device.

Impact on Form, Fit, Function, Quality or Reliability

No impact

Proposed First Ship Date for Change:

November 7, 2016

Last Date of Manufacture of the Unchanged Product:

N/A

Key Material Differences

	Site	
Material	ChipMOS	ASE-K
Mold Compound	Hitachi CEL-9740HF	SUMITOMO EME-G631H
Wire	Au 1 mil diameter 4N	Au 1 mil diameter 4N
Lead Frame	Copper7025	Alloy 42
BLT1 Epoxy	YIZBond 8143	YIZBond 8143
BLT2 Epoxy	Nitto EM710CA	Hitachi FH-900-25 (DAF)
BLT3 Epoxy	Henkel QMI550	Henkel QMI550
Top Shield P/N	ESJ85N44AT2EA	ESJ85N44AT2EA
Bottom Shield P/N	ESJ85N44AB2EA	ESJ85N44AB2EA
Plating	Matte Sn	Matte Sn

Product Identifier

Assembly site code = H for ChipMOS Taiwan

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Supplier Qual Plan Schedule and Results

Qualification is complete and a report is available on request.

Date Qualification Samples Are Available:

Now

Acceptance of Change

Everspin will consider this change accepted unless specific conditions for acceptance are provided in writing within 30 days of receipt of this notice.

Contact Information	**Sample Information** ☑ **Samples Available Now**
Joe O’Hare Director, Product Marketing Everspin Technologies joe.ohare@everspin.com (512) 410-3651 x224	Contact Everspin sales: http://www.everspin.com/contact-us-everspin-technologies If using the on-line sample request please refer to this PCN # to receive samples.

Originator

Date 10/3/2016	*Title* Marketing Director	*Name* Joe O’Hare

Approval and Release

Date *10/3/2016*	*Title* *Director of Quality*	*Name* *Mehar Mahal*
Date 10/3/2016	*Title* VP of Sales and Marketing	*Name* Scott Sewell
Date 10/3/2016	*Title* VP of Business Development and Supply Chain	*Name* Angelo Ugge

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REVISION SHEET

Name	Description of Revision & Writer	Rev. No	Revision Date
Joe O'Hare	Initial release	0.0	10/13/2016
Paul Drobny	Corrected ChipMOS mold compound from SUMITOMO EME-G631H to Hitachi CEL-9740HF. Updated Everspin logo.	1.0	5/30/2019

Revision Approval and Release		
Date 5/30/2019	*Title* *Director of Quality*	*Name* Khaldoun Barakat